Special Issue

Innovations in 3D Printing Technologies: From Microfabrication to Functional Applications

Message from the Guest Editor

We are pleased to announce the Special Issue *"Innovations in 3D Printing Technologies: From Microfabrication to Functional Applications"* in *Micromachines*. This issue aims to highlight cutting-edge research on 3D printing in design, fabrication, engineering, materials science, sustainability, and computational applications. Topics of interest include:

- Additive/hybrid manufacturing
- 3D prototyping, simulation & AI applications
- Novel 3D printing technologies & material optimization
- Testing methods for 3D-printed parts
- Sustainable approaches & multi-material techniques
- Computational design in 3D printing

All submissions will undergo peer review and be fully open access upon publication. We look forward to your contributions!

Guest Editor

Prof. Dr. Panagiotis Kyratsis
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Deadline for manuscript submissions

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About the Journal

Message from the Editor-in-Chief

You are invited to contribute research articles or comprehensive reviews for consideration and publication in *Micromachines* (ISSN 2072-666X). *Micromachines* is published in the open access format. Research articles, reviews and other contents are released on the internet immediately after acceptance. The scientific community and the general public have unlimited free access to the content as soon as it is published. As an open access journal, *Micromachines* is supported by the authors or their institutes by payment of article processing charges (APC) for accepted papers. We are pleased to welcome you as our authors.

Editor-in-Chief

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